

# SOT1133-1

plastic thermal enhanced extremely thin quad flat package;  
no leads; 60 terminals; UTLP based, 0.5 mm pitch, 5 mm x 5  
mm x 0.5 mm body

19 August 2021

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HXQFN60U
<b>Package type industry code</b>	HXQFN60U
<b>Package style descriptive code</b>	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	09-04-2010
<b>Manufacturer package code</b>	SOT1133-1

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.9	5	5.1	mm
seated height	0.46	0.48	0.5	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	60	-	

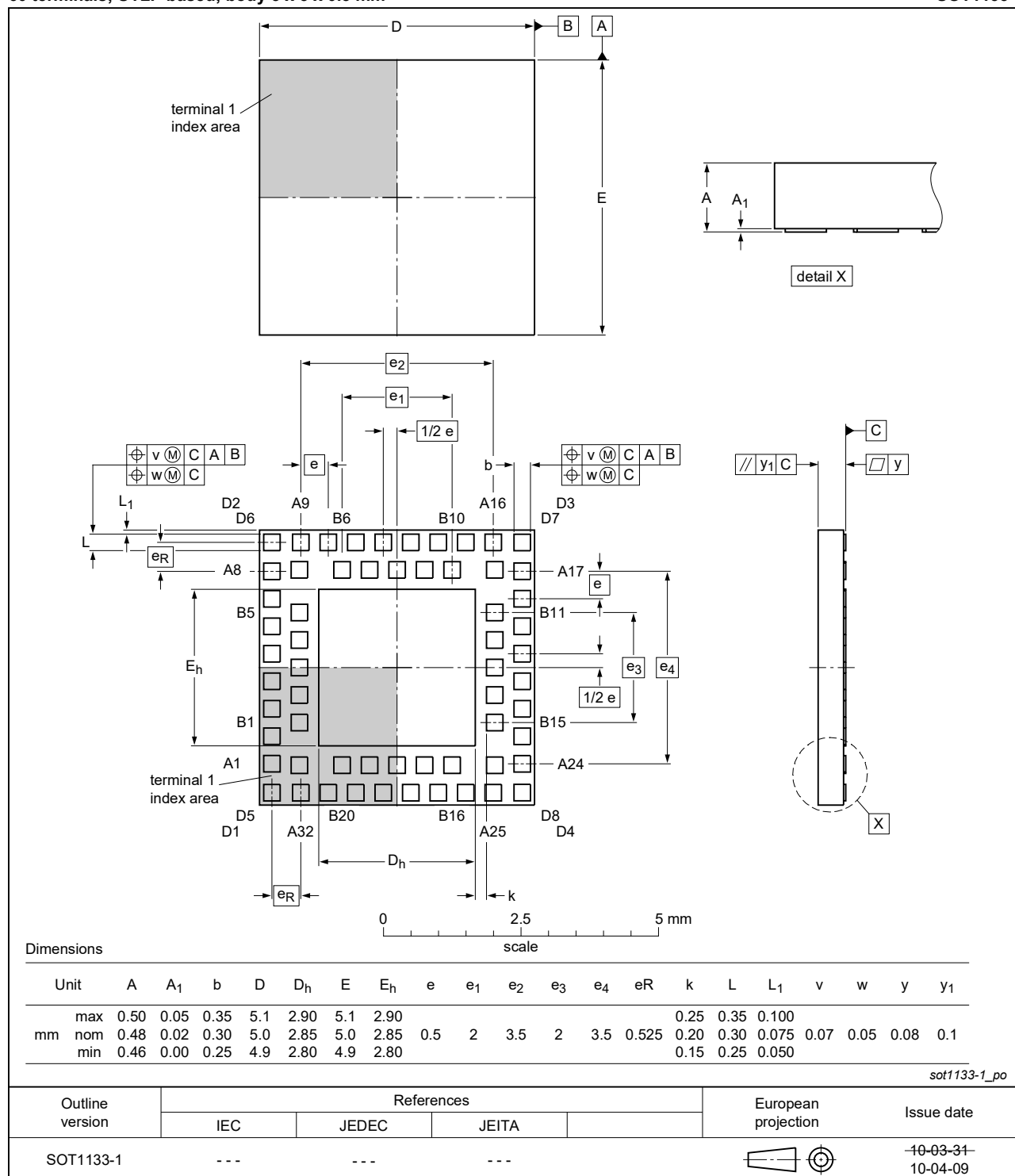


plastic thermal enhanced extremely thin quad flat package; no leads; 60 terminals; UTLT based, 0.5 mm pitch, 5 mm x 5 mm x 0.5 mm body

## 2 Package outline

**HXQFN60U:** plastic thermal enhanced extremely thin quad flat package; no leads; 60 terminals; UTLP based; body 5 x 5 x 0.5 mm

**SOT1133-1**



**Figure 1. Package outline HXQFN60U (SOT1133-1)**

plastic thermal enhanced extremely thin quad flat package; no leads; 60 terminals; UTLP based, 0.5 mm pitch, 5 mm x 5 mm x 0.5 mm body

3 Soldering

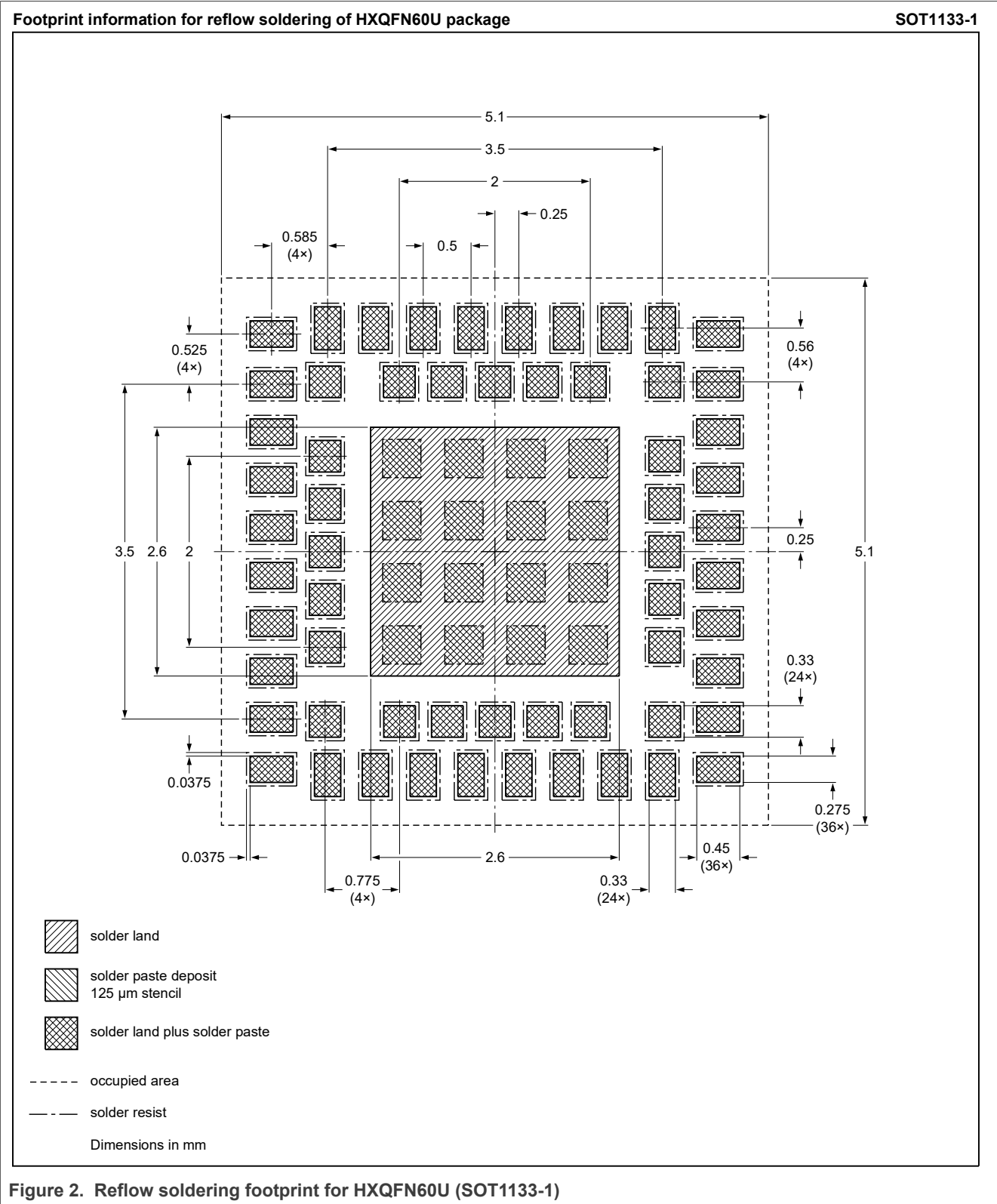


Figure 2. Reflow soldering footprint for HXQFN60U (SOT1133-1)

plastic thermal enhanced extremely thin quad flat package; no leads; 60 terminals; UTLP based, 0.5 mm pitch, 5 mm x 5 mm x 0.5 mm body

## 4 Legal information

---

### Disclaimers

**Limited warranty and liability** — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

**Right to make changes** — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

plastic thermal enhanced extremely thin quad flat package; no leads; 60 terminals; UTLP based, 0.5 mm pitch, 5 mm x 5 mm x 0.5 mm body

Contents

1	Package summary .....	1
2	Package outline .....	2
3	Soldering .....	3
4	Legal information .....	4